

# Bill of Materials

TI DESIGNS

Part #

Literature #

DESIGNATOR	QUANTITY	VALUE	DESCRIPTION	SIZE	PART NUMBER	MANUFACTURER
U1, U2	2	THS3091	High-Voltage, Low-Distortion, Current-Feedback Op Amp	SOIC-8-PP	THS3091DDA (Rails, 75)	TI
					THS3091DDAR (Tape and Reel, 2500)	TI
R1	1	49.9	Resistor, Chip, 1/16W, 1%	1206	Std	Std
R2_1,R2_2	2	249	Resistor, Chip, 1/16W, 1%	1206	Std	Std
R3_1,R3_2	2	1k	Resistor, Chip, 1/16W, 1%	1206	Std	Std
R4_1,R4_2	2	100	Resistor, Chip, 1/16W, 1%	1206	Std	Std
R5_1,R5_2	2	25	Resistor, Chip, 1/16W, 1%	1206	Std	Std
C1,C2	2	2.2uF	Capacitor, Tantalum, 50V, X7R, 10%	1206	Std	Std
C3,C4,C5,C6,C7	5	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	1206	Std	Std
L1,L2	2		Emi-Suppression Ferrite Chip (populate with 0R if not desired)	1206	1206 B 900 R	Steward Li
In, Out	2		SMA or SMB Board Jack		142-0701-801	Johnson
TB	1		Terminal Block, 2.5mm Centers		ED555/3DS	On-Shore

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